

D1 a bare die electronic device having a top, a bottom, sides, and a plurality of terminals, including a non-top terminal, the device being disposed in the recess, and wherein the non-top terminal is electrically coupled to the conductive region.

D2 9. (twice amended) An electronic component according to claim 1, wherein the device is a vertical device and the bottom of the device is coupled to the recess.

D3 14. (twice amended) An electronic component comprising:
an electronic component package including a silicon wafer having a recess, the recess including a first conductive region; and
a bare die electronic device having a top, a bottom, sides, and a plurality of terminals, including a non-top terminal and a top terminal, the device being disposed in the recess, wherein the non-top terminal is electrically coupled to the first conductive region and the top terminal is electrically coupled to a second conductive region, and wherein at least a portion of the first and second conductive regions are essentially planar.

D4 16. (amended) An electronic component comprising:
an electronic device package including a silicon wafer having a recess, the recess including a conductive region; and
an electronic device having a top, a bottom, sides, and a plurality of terminals, including a non-top terminal located in a region other than the top of the device, the device being disposed in the recess, wherein the non-top terminal is electrically coupled to the conductive region.

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21. (amended) An electronic component comprising:

an electronic device having a first terminal and a second terminal,

wherein a first dimension is defined therebetween;

an electronic device package having a first surface, the package including a silicon wafer having a recess on the first surface that has a depth that is substantially equal to the first dimension, the package further having a layer of metal applied to the recess and to a portion of the first surface, wherein the electronic device resides within the recess and the second terminal is coupled to the layer of metal; and

a layer of insulation coupling the electronic device to the silicon wafer.

22. (amended) An electronic component according to claim 21, further comprising:

a first contact coupled to the first terminal; and

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a second contact coupled to the metal residing on the first surface of the package.

32. (amended) An electronic component comprising:

a non-molded electronic component package having a package top and a silicon wafer including a recess;

a planar bare die electronic device having a top, a bottom, sides, and a plurality of contacts, the device being disposed in the recess; and

a planarizing material filling the recess not occupied by the device to substantially create a level plane that includes the top of the device.

In the Drawings: